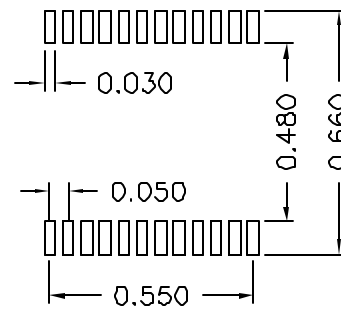
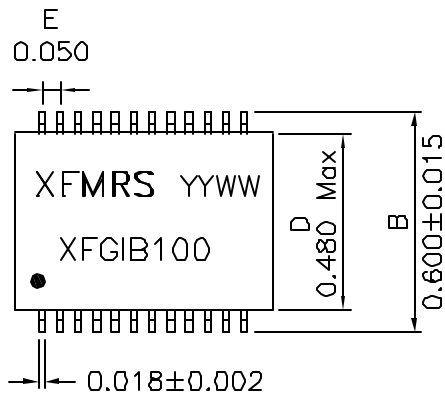
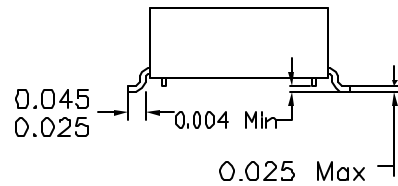
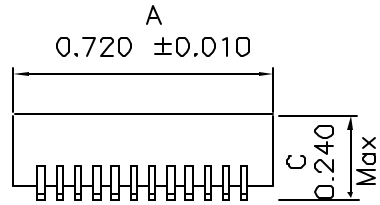
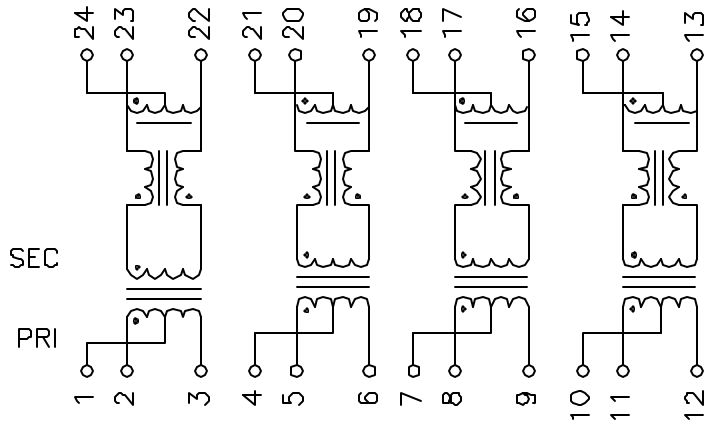


### 1. Mechanical Dimensions:



SUGGESTED PAD LAYOUT

### 2. Schematic:



DOC REV: A/9

### 3. Electrical Specifications: @25°C

ISOLATION: 1500 Vrms

TURNS RATIO: (PRI/SEC) 1CT:1CT ±2%

OCL: 350uH MIN @100KHz 100mV 8mADC

Rise Time: 1.75ns Max.

INSERTION LOSS: -1.0dB MAX @1MHz-100MHz

RETURN LOSS: -18dB Min @1-30MHz

-15dB Min @40MHz -13.1dB Min @50MHz

-12dB Min @60-80MHz -10dB Min @100MHz

Differential to Common Mode Rejection:

-43dB Min @30MHz -37dB Min @80MHz

-33dB Min @100MHz

CMRR: -30dB Min @1-100MHz

Crosstalk: -45dB Min @30MHz

-40dB Min @60MHz -35dB Min @100MHz

Notes:

1. Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004" (0.102mm)
9. Moisture Sensitivity: Level 3
10. Electrical and mechanical specifications 100% tested
11. RoHS Compliant Component

<b>XFMRS Inc</b>		Title: 1000BASE-T Modules	
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in INCH	P/N: XFGIB100		REV. A
	DWN.	Juan Mao	Sep-12-04
SCALE 2:1 SHT 1 OF 1	CHK.	YK Liao	Sep-12-04
	APP.	Joe Huff	Sep-12-04